ABSOLUTE MAXIMUM RATINGS

V _{CC} to GND0.3V to +4.0V
$Q_{-}, \overline{Q}_{-}, CLK_{-}, CLK_{-}SEL_{+}$
CLK_EN to GND0.3V to (V _{CC} + 0.3V)
Continuous Output Current50mA
Surge Output Current100mA
Continuous Power Dissipation ($T_A = +70^{\circ}C$)
20-Pin TSSOP (derate 11mW/°C)879.1mW
20-Pin 4mm × 4mm Thin QFN (derate 16.9mW/°C)1349.1mW
Junction-to-Ambient Thermal Resistance in Still Air
20-Pin TSSOP+91°C/W
20-Pin 4mm × 4mm Thin QFN+59.3°C/W

Junction-to-Case Thermal Resistance	
20-Pin TSSOP	+20°C/W
20-Pin 4mm × 4mm Thin QFN	+2°C/W
Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Soldering Temperature (10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

 $(V_{CC}=3.0V\ to\ 3.6V,\ outputs\ terminated\ with\ 50\Omega\ \pm1\%\ to\ (V_{CC}\ -2V),\ CLK_SEL=V_{CC}\ or\ GND,\ CLK_EN=V_{CC},\ T_A=-40^{\circ}C\ to\ +85^{\circ}C,\ unless\ otherwise\ noted.$ Typical values are at $V_{CC}=3.3V,\ T_A=+25^{\circ}C.$) (Notes 1, 2, and 3)

PARAMETER	SYMBOL	С	MIN	TYP	MAX	UNITS		
INPUTS (CLK0, CLK1, CLK_SI	EL, CLK_EN)	•		•			•	
Innert High Voltage	\/	Cierro 1	CLK0, CLK1	2		V _{CC}	V	
Input High Voltage	V _{IH}	Figure 1	CLK_EN, CLK_SEL	2		V _C C	j ^v	
Input Low Voltage	V.,	Figure 1	CLK0, CLK1	0		1.3	\/	
Input Low Voltage	VIL	Figure 1	CLK_EN, CLK_SEL	0		0.8	V	
	lu.	CLK0, CLK1, CL	K_SEL = V _{CC}			150	μА	
Input High Current	liH	CLK_EN = VCC		-5		+5		
Input Low Current	I	CLK0, CLK1, CLK_SEL = GND		-5		+5	μΑ	
	lıL	CLK_EN = GND	-150					
Input Capacitance	CIN	CLK0, CLK1, CL			4	рF		
OUTPUTS (Q_, Q_)								
Single-Ended Output High Voltage	V _{OH}	Figure 1		V _{CC} -		V _{CC} -	V	
Single-Ended Output Low Voltage	V _{OL}	Figure 1	V _{CC} - 2.0		V _{CC} - 1.7	V		
Differential Output Voltage	V _{OD}	Figure 1, V _{OD} = V _{OH} - V _{OL}		0.6		0.85	V	
SUPPLY		•		•			•	
Supply Current (Note 5)	Icc					25	mA	

AC ELECTRICAL CHARACTERISTICS

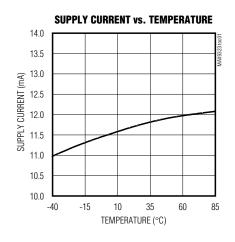
 $(V_{CC}=3.0V\ to\ 3.6V,\ outputs\ terminated\ with\ 50\Omega\ \pm1\%\ to\ (V_{CC}\ -2V),\ f_{IN}<266MHz,\ input\ duty\ cycle=50\%,\ input\ transition\ time=1.1ns\ (20\%\ to\ 80\%),\ V_{IH}=V_{CC},\ V_{IL}=GND,\ CLK_SEL=V_{CC}\ or\ GND,\ CLK_EN=V_{CC},\ T_A=-40^{\circ}C\ to\ +85^{\circ}C,\ unless\ otherwise\ noted.$ Typical values are at $V_{CC}=3.3V,\ T_A=+25^{\circ}C.)$ (Note 4)

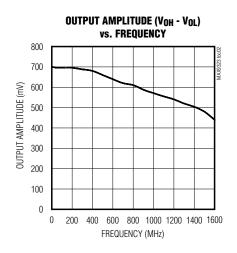
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Switching Fraguency	r.	V _{OH} - V _{OL} ≥ 0.6V	266	800		MHz
Switching Frequency	fMAX	V _{OH} - V _{OL} ≥ 0.3V	1500			IVIIIZ
Propagation Delay	tphl, tplh	CLK0 or CLK1 to Q_, Q_, Figure 1 (Note 6)	100	450	600	ps
Output-to-Output Skew	tskoo	(Note 7)			30	ps
Part-to-Part Skew	tskpp	(Note 8)			150	ps
Output Rise Time	t _R	20% to 80%, Figure 1	100	203	300	ps
Output Fall Time	tF	80% to 20%, Figure 1	100	198	300	ps
Output Duty Cycle	ODC		48	50	52	%
Added Random Jitter	t _{RJ}	f _{IN} = 266MHz, clock pattern (Note 9)		1.7	3	ps(RMS)
Added Jitter (Note 9)	t _A J	V _{CC} = 3.3V with 25mV superimposed sinusoidal noise at 100kHz			10	ps(P-P)

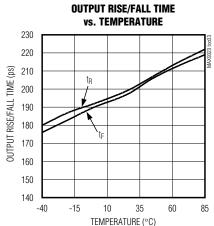
- Note 1: Measurements are made with the device in thermal equilibrium.
- Note 2: Positive current flows into a pin. Negative current flows out of a pin.
- Note 3: DC parameters are production tested at T_A = +25°C and guaranteed by design over the full operating temperature range.
- Note 4: Guaranteed by design and characterization. Limits are set at ±6 sigma.
- Note 5: All pins open except V_{CC} and GND.
- Note 6: Measured from the 50% point of the input to the crossing point of the differential output signal.
- Note 7: Measured between outputs of the same part at the differential signal crosspoint for a same-edge transition.
- Note 8: Measured between outputs of different parts at the differential signal crosspoint under identical conditions for a same-edge transition.
- Note 9: Jitter added to the input signal.

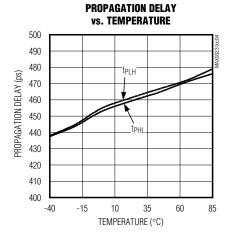
Typical Operating Characteristics

 $(V_{CC} = 3.3V, outputs terminated to (V_{CC} - 2V) through 50\Omega, CLK_SEL = V_{CC} or GND, CLK_EN = V_{CC}, T_A = +25^{\circ}C.)$









Pin Description

PIN			FUNCTION					
TSSOP	QFN	NAME	FUNCTION					
1	18	GND	Ground. Provide a low-impedance connection to the ground plane.					
2	19	CLK_EN	Synchronous Output Enable. Connect CLK_EN to V_{CC} or leave floating to enable the differential outputs. Connect CLK_EN to GND to disable the differential outputs. When disabled, Q_ asserts low and \overline{Q} asserts high. An internal 51k Ω pullup resistor to V_{CC} allows CLK_EN to be left floating.					
3	20	CLK_SEL	Clock Select Input. Connect CLK_SEL to V_{CC} to select the CLK1 input. Connect CLK_SEL to GND or leave floating to select the CLK0 input. Only the selected CLK_ signal is reproduced at each output. An internal $51k\Omega$ pulldown resistor to GND allows CLK_SEL to be left floating.					
4	1	CLK0	LVCMOS Clock Input. When CLK_SEL = GND, each set of outputs differentially reproduces CLK0. An internal 51k Ω pulldown resistor to GND forces the outputs (Q_, \overline{Q}) to differential low when CLK0 is left open or at GND, CLK_SEL = GND, and the outputs are enabled.					
5, 7, 8, 9	2, 4, 5, 6	N.C.	No Connect. Not internally connected.					
6	3	CLK1	LVCMOS Clock Input. When CLK_SEL = V _{CC} , each set of outputs differentially reproduces CLK1. An internal 51k Ω pulldown resistor to GND forces the outputs (Q_, \overline{Q}) to differential low when CLK1 is left open or at GND, CLK_SEL = V _{CC} , and the outputs are enabled.					
10, 13, 18	7, 10, 15	Vcc	Positive Supply Voltage. Bypass V _{CC} to GND with three 0.01µF and one 0.1µF ceramic capacitors. Place the 0.01µF capacitors as close to each V _{CC} input as possible (one per V _{CC} input). Connect all V _{CC} inputs together, and bypass to GND with a 0.1µF ceramic capacitor.					
11	8	Q3	Inverting Differential LVPECL Output. Terminate $\overline{Q3}$ to (V _{CC} - 2V) with a 50 Ω ±1% resistor.					
12	9	Q3	Noninverting Differential LVPECL Output. Terminate Q3 to (V _{CC} - 2V) with a 50 Ω ±1% resistor.					
14	11	Q2	Inverting Differential LVPECL Output. Terminate $\overline{Q2}$ to (V _{CC} - 2V) with a 50 Ω ±1% resistor.					
15	12	Q2	Noninverting Differential LVPECL Output. Terminate Q2 to (V _{CC} - 2V) with a 50 Ω ±1% resistor.					
16	13	Q1	Inverting Differential LVPECL Output. Terminate $\overline{Q1}$ to (V _{CC} - 2V) with a 50 Ω ±1% resistor.					
17	14	Q1	Noninverting Differential LVPECL Output. Terminate Q1 to (V _{CC} - 2V) with a 50 Ω ±1% resistor.					
19	16	Q0	Inverting Differential LVPECL Output. Terminate $\overline{Q0}$ to (V _{CC} - 2V) with a 50 Ω ±1% resistor.					
20	17	Q0	Noninverting Differential LVPECL Output. Terminate Q0 to (V _{CC} - 2V) with a 50 Ω ±1% resistor.					

Detailed Description

The MAX9323 low-skew, low-jitter, clock and data driver distributes one of two single-ended LVCMOS input signals to four differential LVPECL outputs. An input multiplexer allows selection of one of the two input signals. The output drivers operate at frequencies up to 1.5GHz. The MAX9323 operates from 3.0V to 3.6V, making it ideal for 3.3V systems.

Data Inputs

Single-Ended LVCMOS Inputs

The MAX9323 accepts two single-ended LVCMOS inputs (CLK0 and CLK1, Figure 1). An internal reference (VCC/2) provides the input thresold voltage for CLK0 and CLK1. CLK_SEL selects the CLK0 input or CLK1 input to be converted to four differential LVPECL signals (see Table 1). Connect CLK_SEL to GND to

select CLK0. Connect CLK_SEL to VCC to select CLK1. CLK0 and CLK1 are pulled to GND through internal $51k\Omega$ resistors, when not connected.

CLK EN Input

CLK_EN enables/disables the differential outputs of the MAX9323. Connect CLK_EN to VCC to enable the differential outputs. The (Q_, $\overline{\rm Q}_-$) outputs are driven to a differential low condition when CLK_EN = GND. Each differential output pair disables following successive rising and falling edges on CLK_, after CLK_EN connects to GND. Both a rising and falling edge on CLK_ are required to complete the enable/disable function (Figure 2).

CLK_SEL Input

CLK_SEL selects which single-ended LVCMOS input signal is output differentially as four LVPECL signals. Connect CLK_SEL to GND to select the CLK0 input.

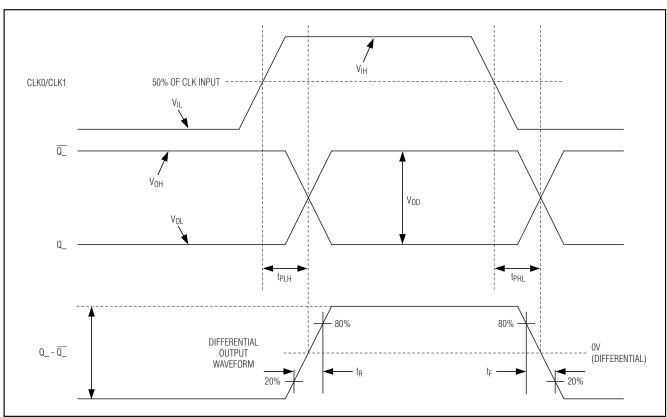


Figure 1. MAX9323 Clock Input-to-Output Delay and Rise/Fall Time

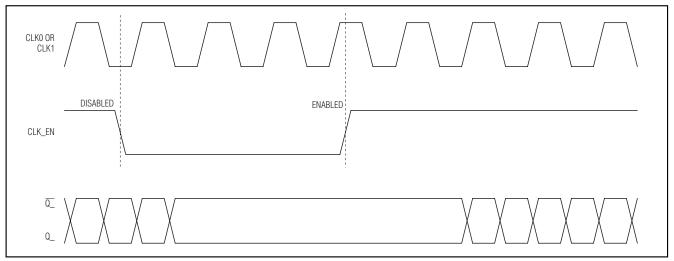


Figure 2. MAX9323 CLK_EN Timing Diagram

Table 1. Control Input Table

	INPUTS		OUTPUTS			
CLK_EN	CLK_EN CLK_SEL SELECTED SOURCE		Q0-Q3	Q0-Q3		
0	0	CLK0	Disabled, pulled to logic low	Disabled, pulled to logic high		
0	1	CLK1	Disabled, pulled to logic low	Disabled, pulled to logic high		
1	0	CLK0	Enabled	Enabled		
1	1	CLK1	Enabled	Enabled		

Connect CLK_SEL to VCC to select the CLK1 input. An internal $51k\Omega$ pulldown resistor to GND allows CLK_SEL to be left floating.

Applications Information

Output Termination

Terminate both outputs of each differential pair through 50Ω to (VCC - 2V) or use an equivalent Thevenin termination. Use identical termination on each output for the lowest output-to-output skew. Terminate both outputs when deriving a single-ended signal from a differential output. For example, using Q0 as a single-ended output requires termination for both Q0 and $\overline{\rm Q0}$.

Ensure that the output currents do not violate the current limits as specified in the *Absolute Maximum Ratings* table. Observe the device's total thermal limits under all operating conditions.

Power-Supply Bypassing

Bypass VCC to GND using three 0.01µF ceramic capacitors and one 0.1µF ceramic capacitor. Place the 0.01µF capacitors (one per VCC input) as close to VCC as possible (see the *Typical Operating Circuit*). Use multiple bypass vias to minimize parasitic inductance.

Circuit Board Traces

Input and output trace characteristics affect the performance of the MAX9323. Connect each input and output to a 50Ω characteristic impedance trace to minimize reflections. Avoid discontinuities in differential imped-

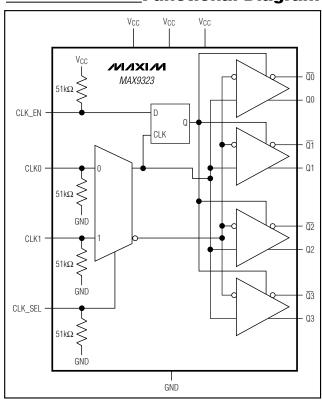
ance and maximize common-mode noise immunity by maintaining the distance between differential traces and avoiding sharp corners. Minimize the number of vias to prevent impedance discontinuities. Minimize skew by matching the electrical length of the traces.

Chip Information

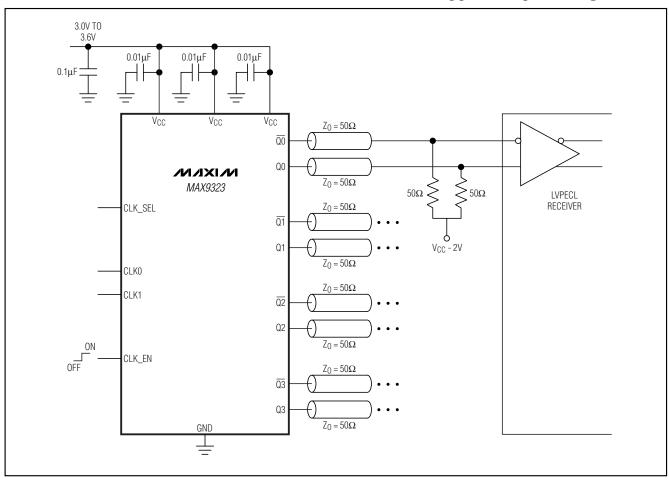
TRANSISTOR COUNT: 4430

PROCESS: BICMOS

Functional Diagram

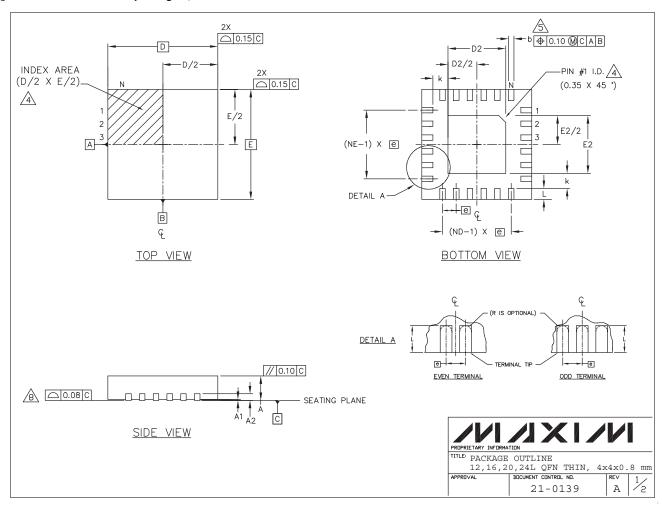


Typical Operating Circuit



Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)

COMMON DIMENSIONS													
PKG	12L 4×4 16L 4×4				20L 4×4			24L 4×4					
REF.	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.	
Α	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	
A1	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05	
A2		0.20 REF	EF 0.20 REF			0.20 REF			0.20 REF				
b	0.25	0.30	0.35	0.25	0.30	0.35	0.20	0.25	0.30	0.18	0.23	0.30	
D	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	
E	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	
е		0.80 BSC	<u>.</u>		0.65 BSC.		0.50 BSC.		0.50 BSC.				
k	0.25	-	-	0.25	-	-	0.25	-	-	0.25	-	-	
L	0.45	0.55	0.65	0.45	0.55	0.65	0.45	0.55	0.65	0.30	0.40	0.50	
N		12			16			20			24		
ND		3		4			5			6			
NE		3		4			5		6				
Jedec Var.		WGGB			WGGC		WGGD−1			WGGD-2			

EXPO:	SED	PAD	VAF	ZND			
PKG.		D2		E2			
CODES	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.	
T1244-2	1.95	2.10	2.25	1.95	2.10	2.25	
T1644-2	1.95	2.10	2.25	1.95	2.10	2.25	
T2044-1	1.95	2.10	2.25	1.95	2.10	2.25	
T2444-1	2.45	2.60	2.63	2.45	2.60	2.63	

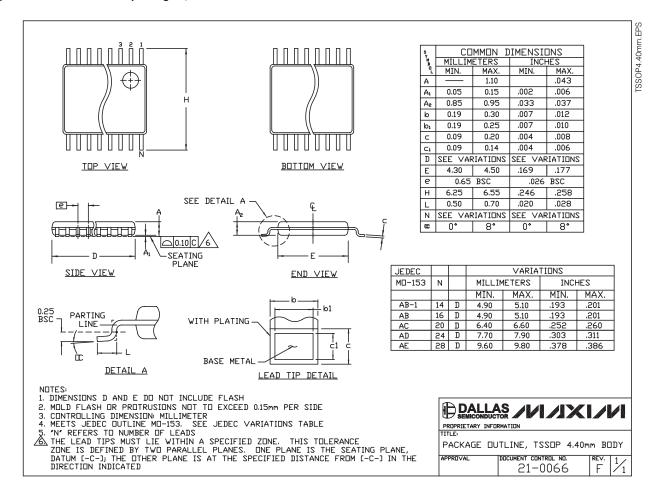
NOTES:

- 1. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
- 3. N IS THE TOTAL NUMBER OF TERMINALS.
- 4\text{\text{THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.
- (S) DIMENSION 6 APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 mm AND 0.30 mm FROM TERMINAL TIP.
- MD AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
- 7. DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
- & COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- 9. DRAWING CONFORMS TO JEDEC MO220.



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



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